

## N-Channel 30-V (D-S) MOSFET

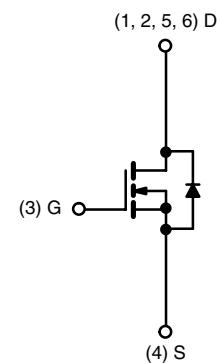
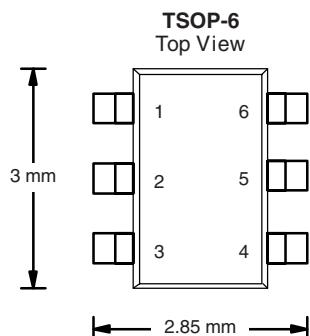
PRODUCT SUMMARY		
$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
30	0.035 at $V_{GS} = 10$ V	6.0
	0.052 at $V_{GS} = 4.5$ V	4.9

### FEATURES

- Halogen free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 %  $R_g$  Tested
- Compliant to RoHS Directive 2002/95/EC



**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**  
Available



**Ordering Information:** Si3456BDV-T1-E3 (Lead (Pb)-free)  
Si3456BDV-T1-GE3 (Lead (Pb)-free and Halogen-free)

**Marking Code:** 6Bxxx

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted					
Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		$V_{DS}$	30		V
Gate-Source Voltage		$V_{GS}$	$\pm 20$		
Continuous Drain Current ( $T_J = 150$ °C) <sup>a</sup>	$T_A = 25$ °C	$I_D$	6.0	4.5	A
	$T_A = 70$ °C		4.8	3.6	
Pulsed Drain Current		$I_{DM}$	$\pm 30$		A
Continuous Source Current (Diode Conduction) <sup>a</sup>		$I_S$	1.7	0.9	
Maximum Power Dissipation <sup>a</sup>	$T_A = 25$ °C	$P_D$	2.0	1.1	W
	$T_A = 70$ °C		1.3	0.7	
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	$t \leq 5$ s	$R_{thJA}$	55	62.5	°C/W
	Steady State		92	110	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	28	40	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

**SPECIFICATIONS**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

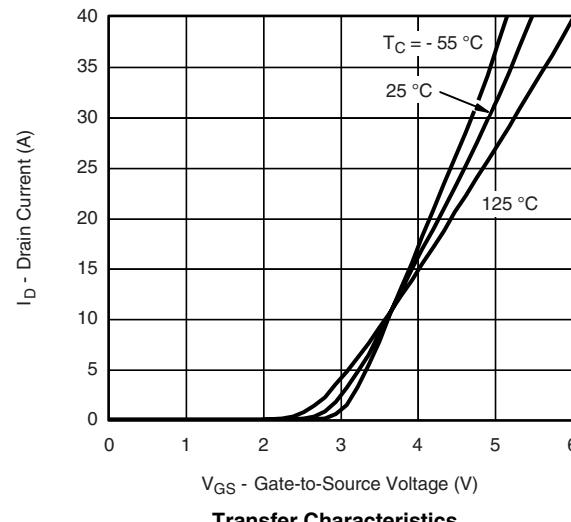
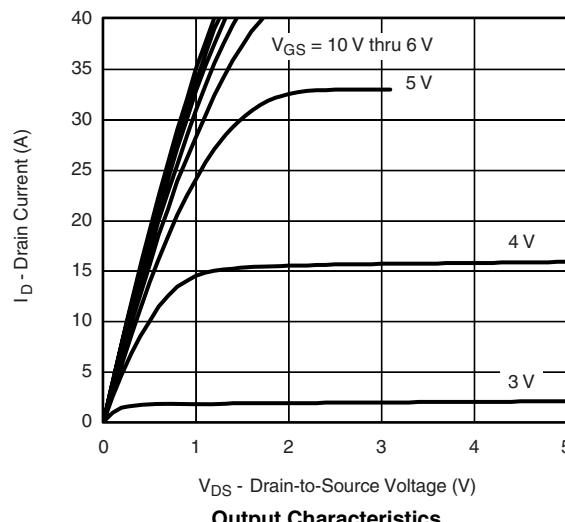
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static</b>							
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	1.0		3.0	V	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}$ , $V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 30 \text{ V}$ , $V_{GS} = 0 \text{ V}$		1		$\mu\text{A}$	
		$V_{DS} = 30 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 55^\circ\text{C}$		5			
On-State Drain Current <sup>a</sup>	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}$ , $V_{GS} = 10 \text{ V}$	30			A	
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}$ , $I_D = 6 \text{ A}$		0.028	0.035	$\Omega$	
		$V_{GS} = 4.5 \text{ V}$ , $I_D = 4.9 \text{ A}$		0.041	0.052		
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 15 \text{ V}$ , $I_D = 6 \text{ A}$		12		S	
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = 1.7 \text{ A}$ , $V_{GS} = 0 \text{ V}$		0.8	1.2	V	
<b>Dynamic<sup>b</sup></b>							
Total Gate Charge	$Q_g$	$V_{DS} = 15 \text{ V}$ , $V_{GS} = 10 \text{ V}$ , $I_D = 6 \text{ A}$		8.6	13	nC	
Gate-Source Charge	$Q_{gs}$			1.8			
Gate-Drain Charge	$Q_{gd}$			1.5			
Gate Resistance	$R_g$	$f = 1 \text{ MHz}$		1.4	2.8	4.8	$\Omega$
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 15 \text{ V}$ , $R_L = 15 \Omega$ $I_D \geq 1 \text{ A}$ , $V_{GEN} = 10 \text{ V}$ , $R_g = 6 \Omega$		10	15	ns	
Rise Time	$t_r$			15	25		
Turn-Off Delay Time	$t_{d(\text{off})}$			25	40		
Fall Time	$t_f$			10	15		
Source-Drain Reverse Recovery Time	$t_{rr}$	$I_F = 1.7 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$		20	40		

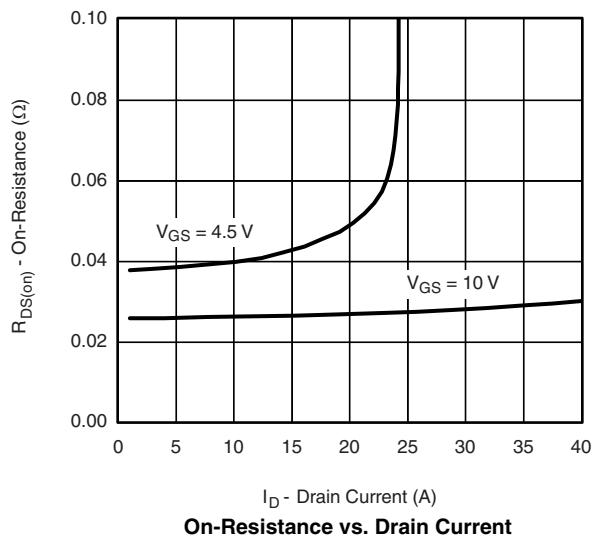
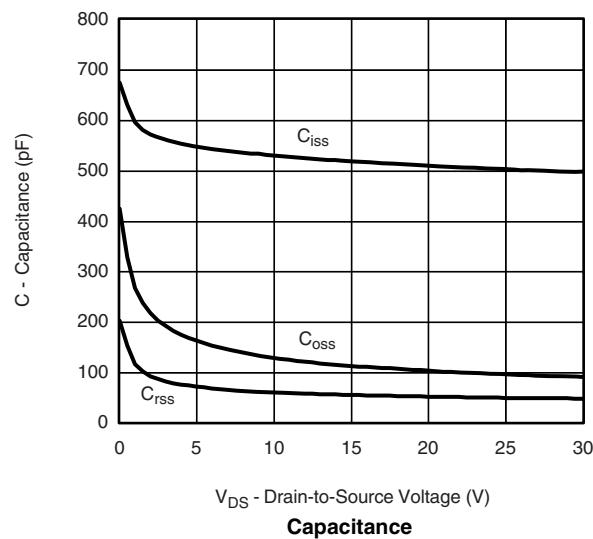
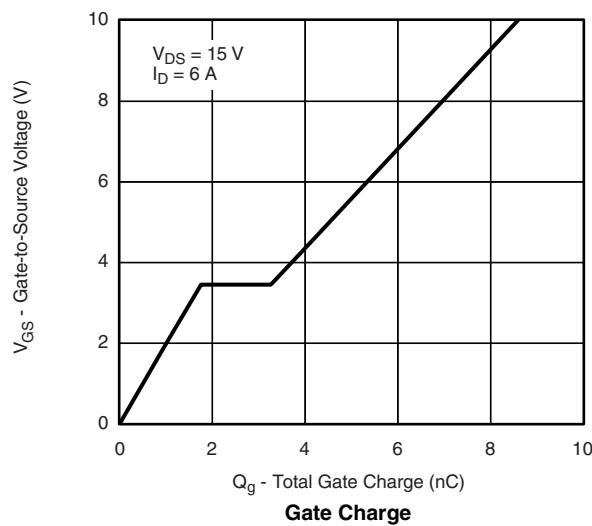
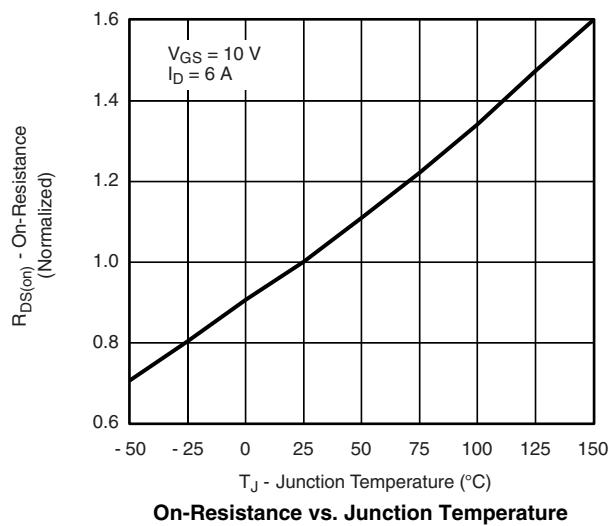
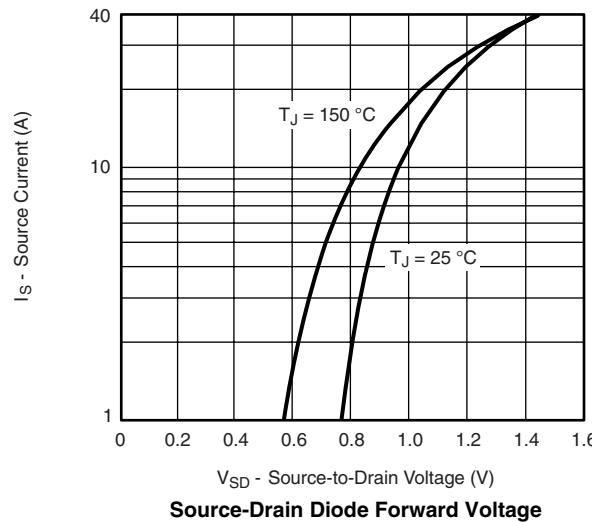
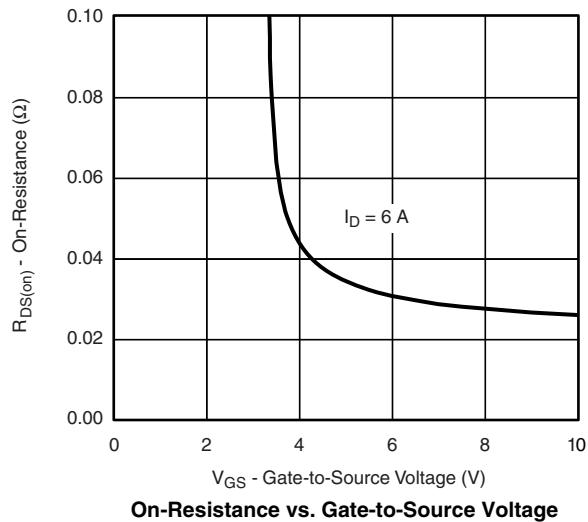
## Notes:

a. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2 \%$ .

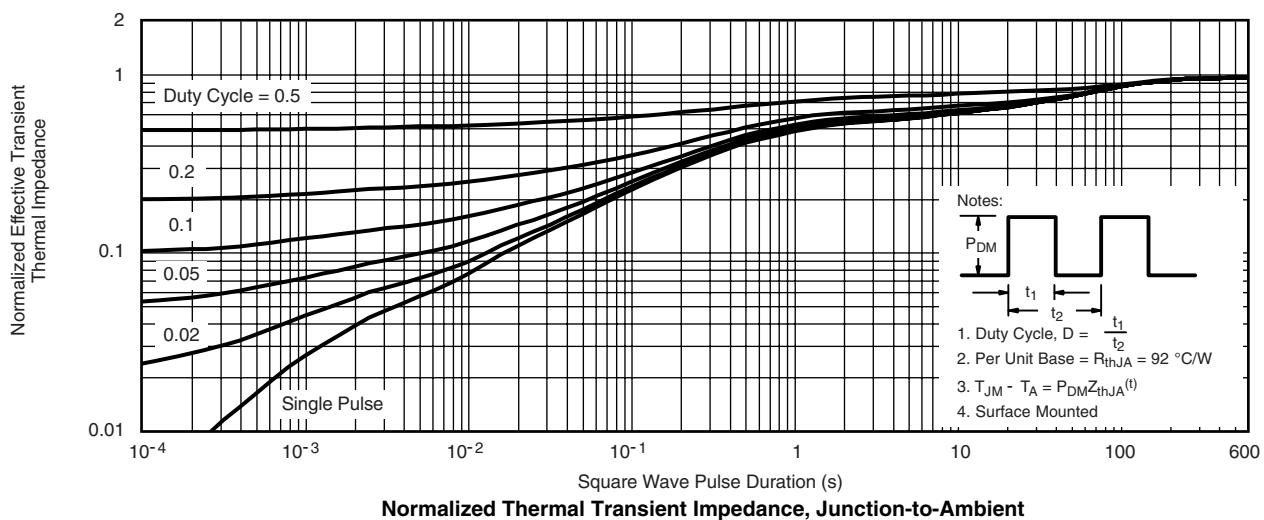
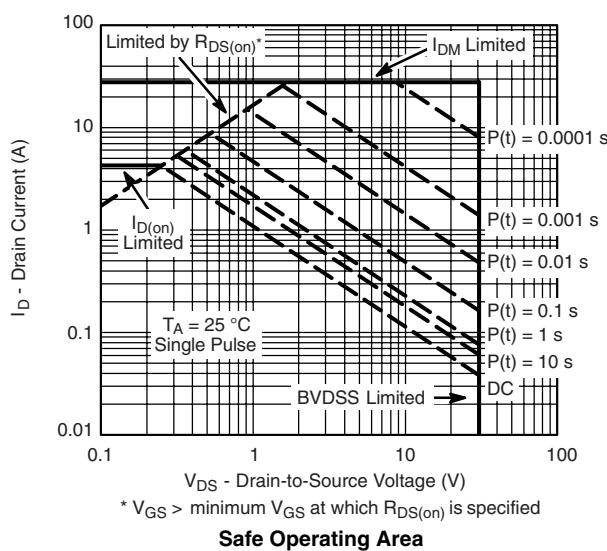
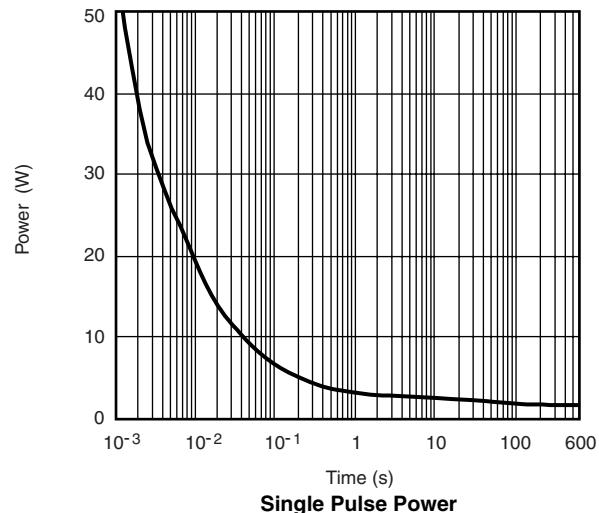
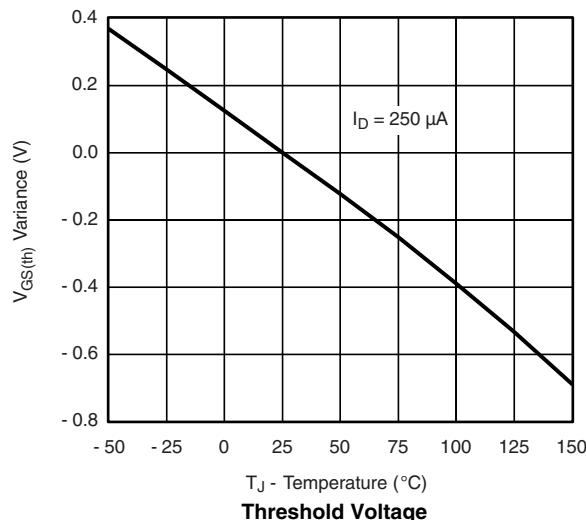
b. Guaranteed by design, not subject to production testing.

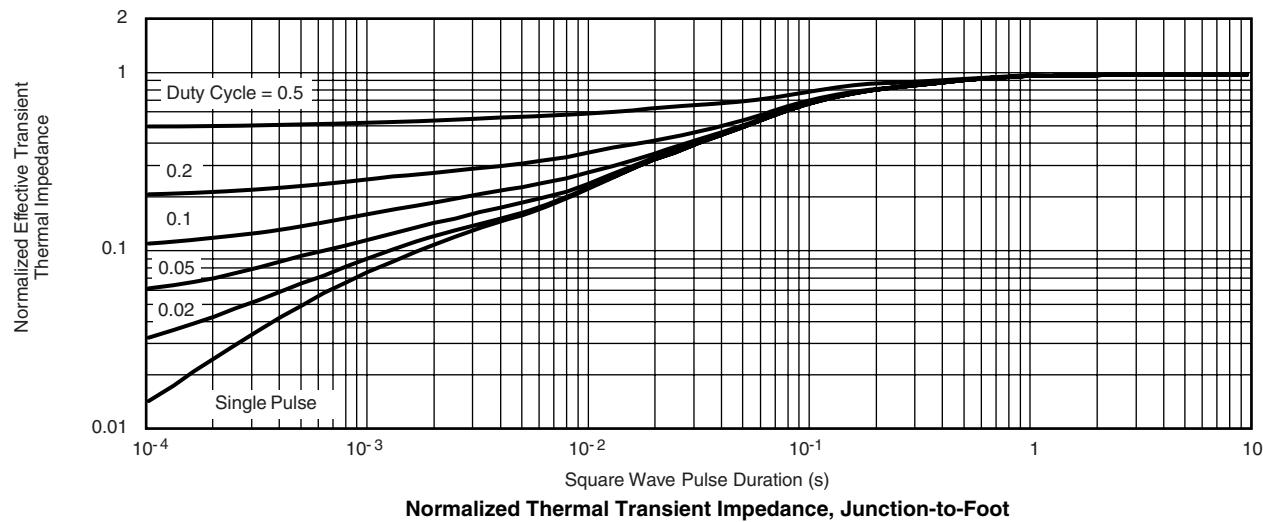
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS**  $25^\circ\text{C}$ , unless otherwise noted

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**On-Resistance vs. Drain Current**

**Capacitance**

**Gate Charge**

**On-Resistance vs. Junction Temperature**

**Source-Drain Diode Forward Voltage**

**On-Resistance vs. Gate-to-Source Voltage**

### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted


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